	Туре	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L4		chip or element or device or die or dice		2004/04/16 15:15
2	BRS	L 5	196835 9	wafer or substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:16
3	BRS	L6	470257 0		USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:23
4	BRS	L7	186046 4	interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:23
5	BRS	L8	701175	stack\$6 or (multi\$6 near2 (chip or element or device or die or dice))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:16

	Туре	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L11	1591	10 near8 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:22
12	BRS	L13	469766	(through adj hole) or through-hole	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:23
13	BRS	L14	148	11 near8 (electrode or pad)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:37
14	BRS	L15	2381	13 near4 (pad or electrode) near8 4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:50
15	BRS	L16	818	13 near4 (pad or electrode) near8 element	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:50

	Туре	L #	Hits	Search Text	DBs	Time Stamp
16	BRS	L17	571	13 near4 (pad or electrode) near4 element	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:50
17	BRS	L18	492	17 and (@ad<20020121)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/04/16 15:51